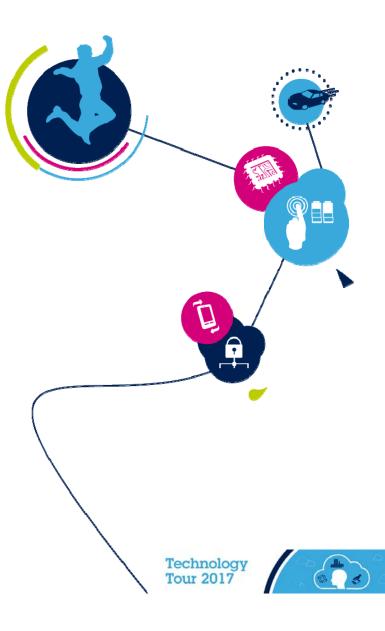
AC-DC SMPS: Up to 15W Application Solutions

Yehui Han – Applications Engineer

April 2017

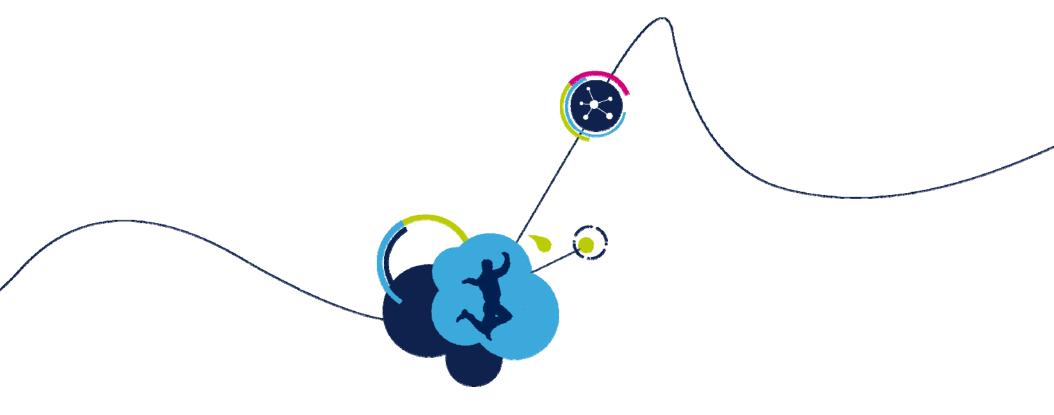




Agenda 2

- Introduction
- Flyback Topology Optimization
- Buck Topology Optimization
- Layout and EMI Optimization
- eDesignSuite Examples





Introduction



Applications 4

Auxiliary Power Supply





















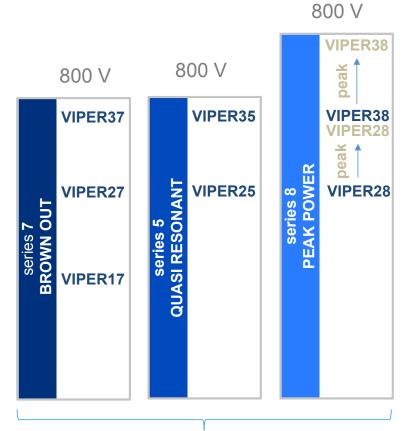




Power MOSFET ON Resistance

Products 5





800 V 800 V Logic level Logic level 800 V 4Ω 7Ω VIPER26 series 1 FEEDBA 20Ω **VIPER0P** VIPER11 series 6 VIPER16 30 Ω VIPER06 VIPER01

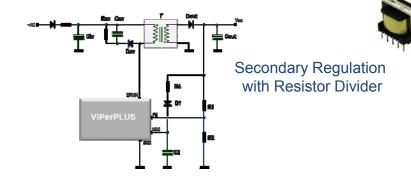
Flyback Safety Isolation





Which Topology? 6

Functional Isolation

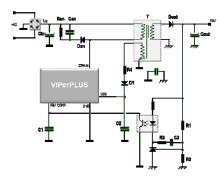


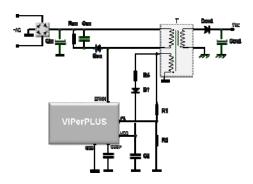
Flyback Converter

Galvanic Isolation For Touchable Outputs

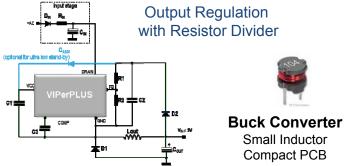
Secondary-Side Regulation With Opto-Coupler For Tight Regulation

Primary-Side Regulation Without Opto-Coupler

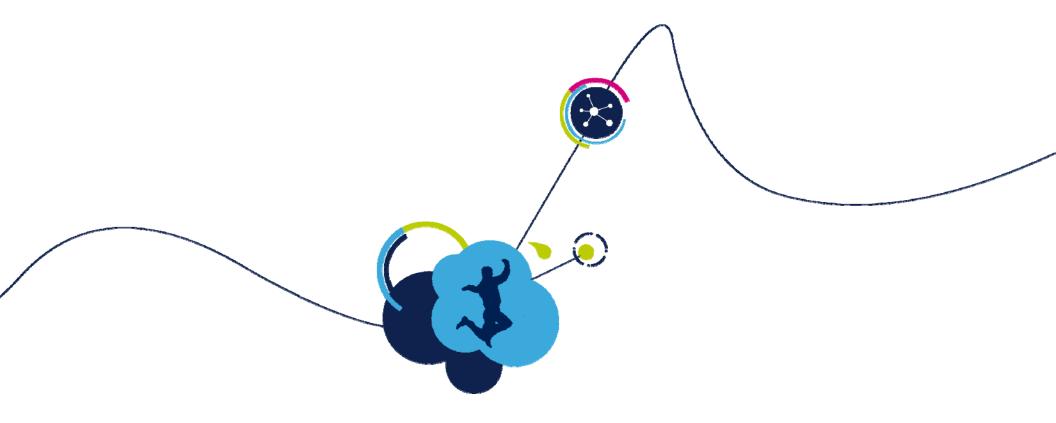




Buck Non-Isolated



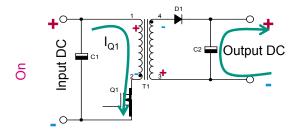


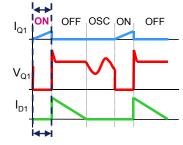


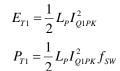
Flyback Topology Optimization

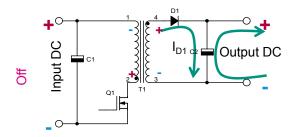


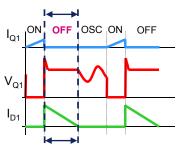
Flyback Operation

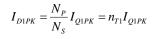






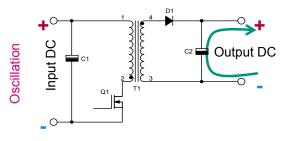


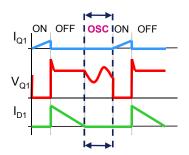




$$E_{T1} = \frac{1}{2} L_S I_{D1PK}^2$$

$$L_S = \frac{L_P}{n_{T1}^2}$$

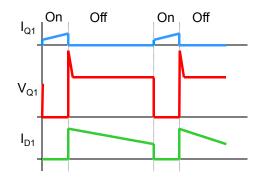






Operation Modes 9

Continuous Mode (CCM)



Benefit

- · Higher power capability
- Lower conduction loss
- Smaller transformer
- · Smaller output caps

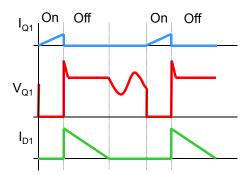
Drawback

- · Not ZCS worse EMI and switching Losses
- · Control instability possible

Where to Use

- · Higher peak power demands
- Lower input voltages, e.g.,110V

Discontinuous Mode (DCM)



Benefits

- · ZCS turn-on of MOSFET
- · ZCS turn-off of diode
- · Single Feedback loop
- Low noise
- · Lower switching cap loss

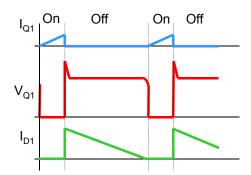
Drawbacks

- EMI due to self-oscillating
- Unused Time slot

Where to Use

· Higher input voltage, e.g., 230V

Transition Mode (TM)



Benefits

- ZCS turn-on of MOSFET
- · ZCS turn-off of Diode
- · Simple feedback loop
- · Low noise

Drawback

· Variable frequency could be problematic

· Where to Use

· When efficiency is a concern



Select Switching Frequency

- Three fixed frequencies: 30±3kHz, 60±4kHz and 115±8kHz
- Priority on transformer size?
 - Higher frequency allows to reduces L_P using less turns and smaller core size
- Priority on power efficiency?
 - Lower frequency allows to improve the efficiency

TYPICAL CORE SIZE VERSUS OPERATING FREQUENCY

Frequency	E10	E13	E16	E20	E25
30 kHz	1.5 W	2 W	4 W	7 W	
60 kHz	3 W	4 W	6 W	13 W	25 W
115/120 kHz	5 W	6 W	8 W	18 W	32 W



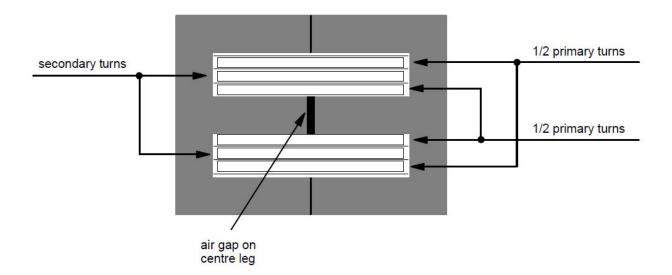
Transformer Design

- Basic specification of transformer include
 - Size, isolation barrier, reflected voltage, peak (or saturation) current, frequency, input voltage range, output voltage and output current range
- Leakage inductance influence power loss, snubber and EMI
 - Typical leakage inductance is 1~3% of primary inductance depending on the transformer structure
 - $P_{Leakage} = \frac{1}{2} L_{Leakage} I_P^2 \times f_S$
- Reflected Voltage V_R is the voltage reflected from secondary output to the primary of transformer



Minimizing L_{leakage} by Interleaving

 Leakage inductance can be reduced by splitting primary winding in 2 halves and sandwiching secondary winding in between





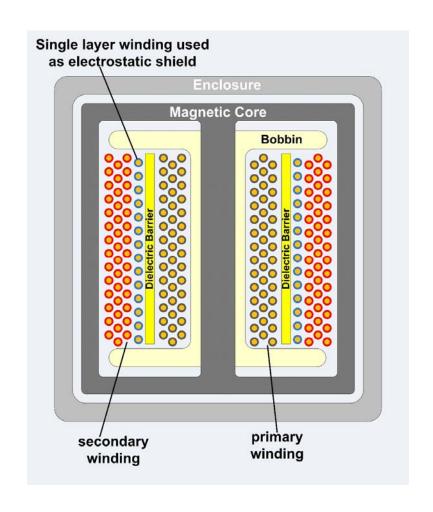
Reflected Voltage Selection 13

- Optimize reflected voltage to set maximum duty cycle. As a rule of thumb, make it equal to minimum DC input voltage
- High reflected voltage means high Vds stress and higher snubber losses
- Lower reflected voltage means higher off time, higher RMS losses and higher primary peak current
- A positive side effect of lower reflected voltage is that it leads to better magnetic coupling between windings, which, in turn, helps to reduce leakage inductance
- On the other hand, consider that a lower reflected voltage involves higher primary peak currents at heavy load



Shielded or Non-Shielded

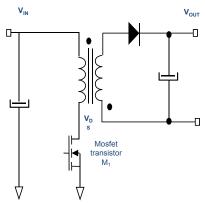
- Shielded transformer has better EMI but larger leakage inductance
- Non-shielded transformer has worse EMI but smaller leakage inductance

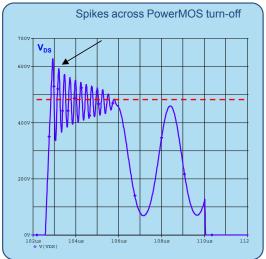


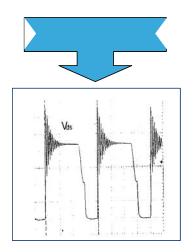


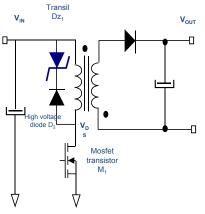
Clamp Circuit 15

Without Clamp Circuit

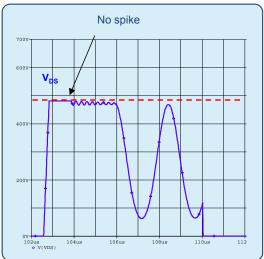






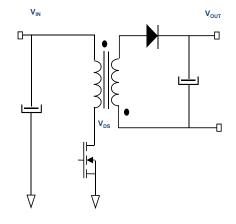


With Clamp Circuit



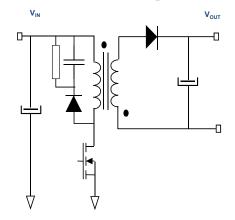


Clamp Implementations —16



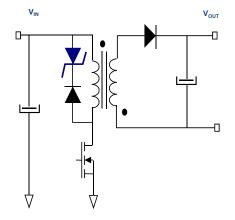


- Test to be performed to know max V_{DS}
- MOS / IGBT to be oversized in voltage (more expensive, efficiency drop)





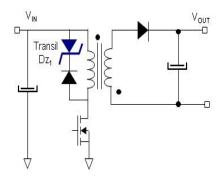
- Slope may vary depending on components
- Margin on V_{DS} is depending on components
- Test to be done for validation



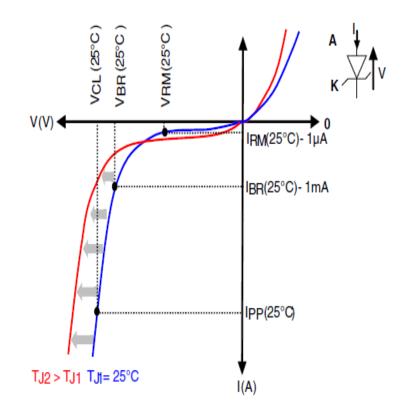
- Maximum clamping voltage only depends on STRVS
- Datasheet/product adapted to repetitive surges
- Margin on V_{DS} can be easily calculated
- Validate with minimal test



New Clamping Technology: STRVS



- VRM is stand-off voltage and must be selected to allow the FET to switch: VRM > VIN + VR
- VCL is the clamping voltage and is critical to choose as close as possible to the application requirement
- Extensive data published on STRVS datasheet makes the selection for the right part easy and robust

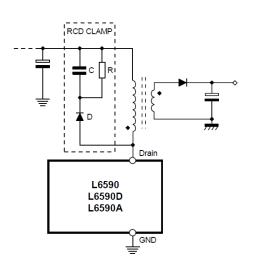




RCD Snubber 18

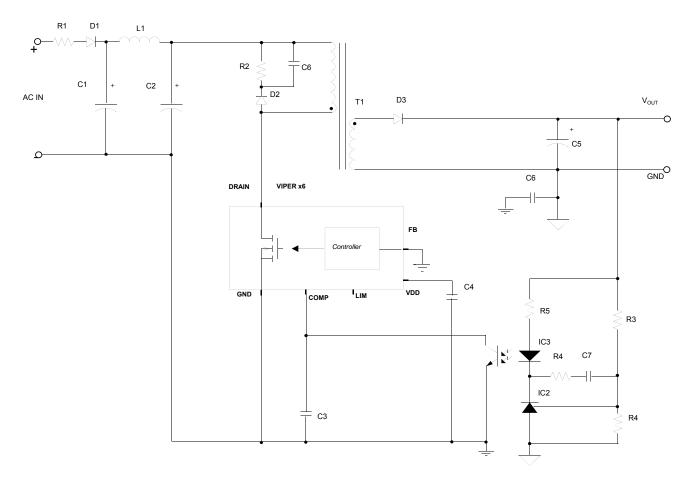
- RCD sizes and values need to be carefully selected. There is a tradeoff between RC values, power dissipation, EMI and clamping effect
- RCD clamp dissipates power even under no-load conditions: there is always the reflected voltage across the clamp resistor R

R	С	V _{CL}	V _{DS} (PK)	EMI	P _{DISS} (R)	Cost
\uparrow	↑	\downarrow	\downarrow	\downarrow	↑	↑
\downarrow	\downarrow	\uparrow	\uparrow	\uparrow	\downarrow	\downarrow



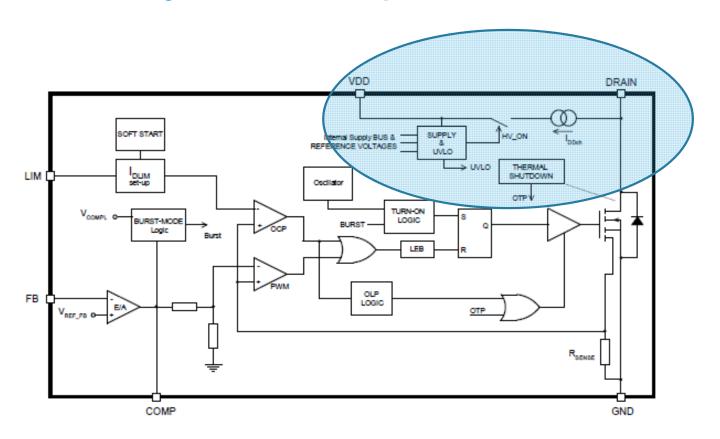


Stand-By Consumption 19



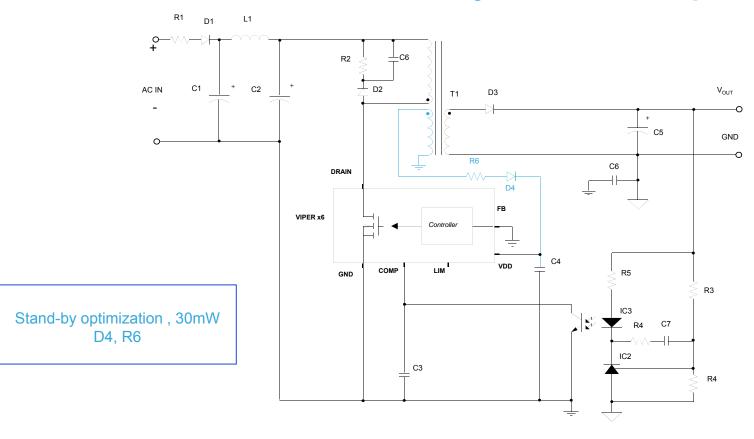


Stand-By Consumption: HV Start-Up 20



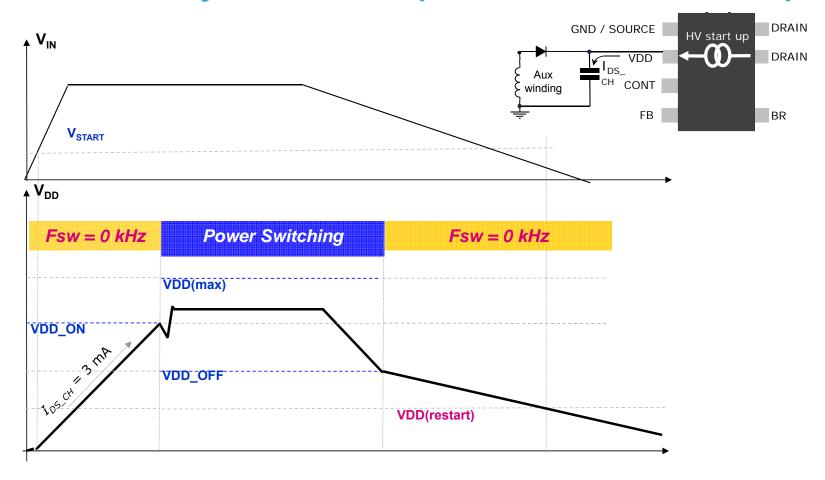


Stand-By Consumption 21



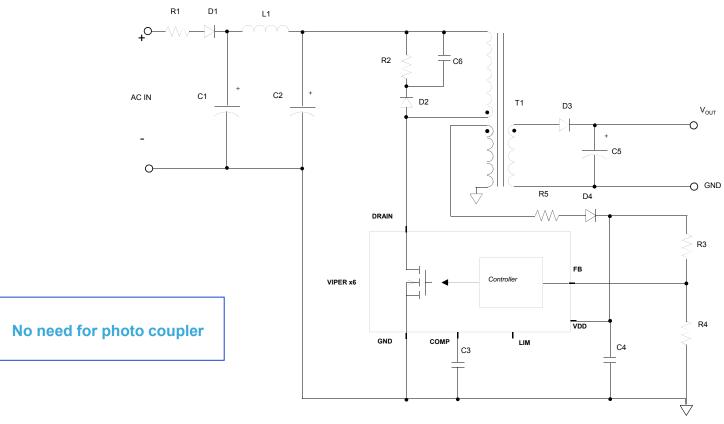


Stand-By Consumption: HV Start-Up



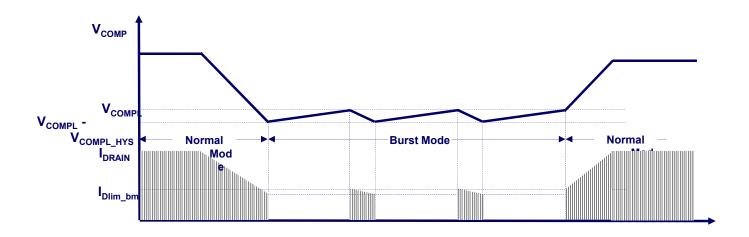


Stand-By Consumption 23





Stand-By Consumption: Burst Mode 24

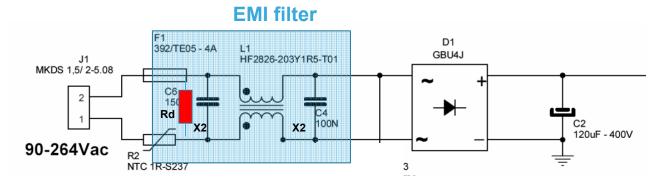


 $V_{COMP} < V_{COMPL}$ starts burst mode

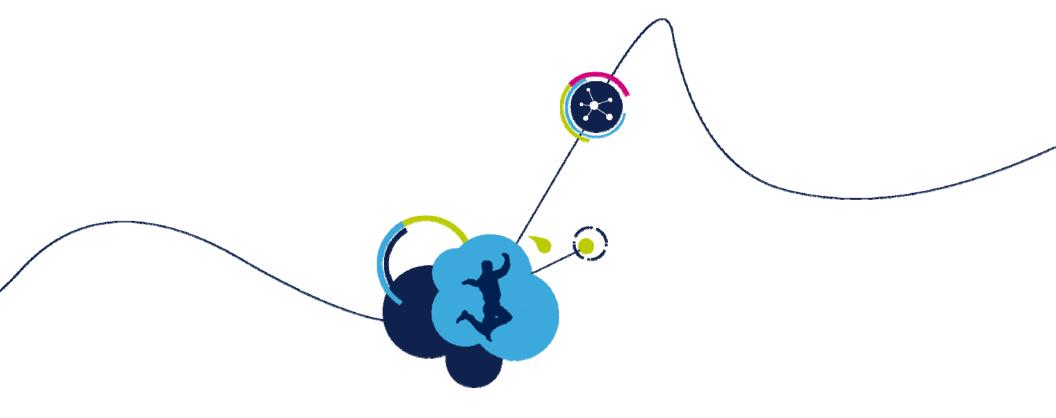


X-Cap Discharge

- The EMI filter in the input of the power converter typically consists of capacitors across the AC mains and CM choke
- According to safety regulations, e.g. UL 1950 and IEC61010-1, capacitors on the mains must be discharged within a given time after the appliances is suddenly disconnected
- A discharge resistor is typically connected in parallel, resulting in additional power losses, as long as the appliance is plugged
- An new function has been recently introduced in order to actively discharge the X capacitor through the HV start-up circuit



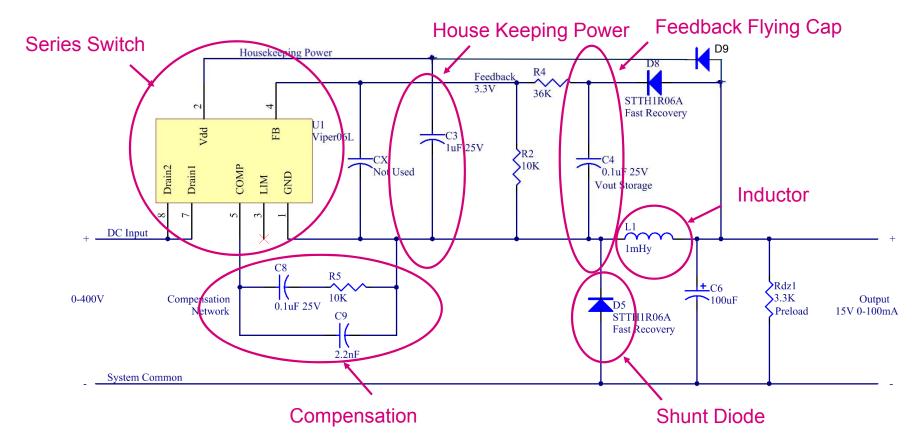




Buck Topology Optimization



Buck Schematic 27





"Flying Capacitor" Feedback Scheme 28

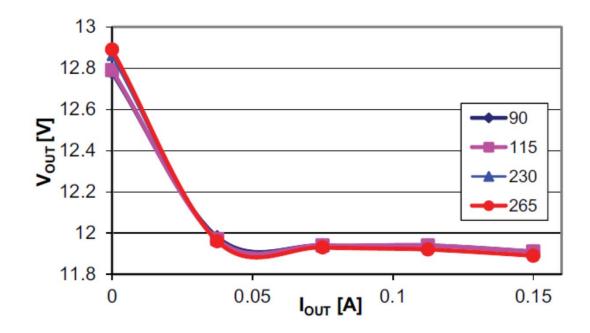
- C4 stores output voltage, transfers level into Viper feedback loop
- R4 R2 discharge C4 slowly
- Load current is required to turn on D5 and D8 to charge C4
- A light load MUST be present to insure diode turn-on
- C4 must hold output voltage information when Viper is in burst mode



"Flying Capacitor" Feedback Scheme (Cont.)

Low cost solution

Minimum load required





Select Switching Frequency 30

SELECT FREQUENCY FOR 5 V OUTPUT BUCK

Vin DC (V)	D (%) 5 V	t _{oN} (μs) for 60 kHz 5 V	t _{on} (µs) for 30 kHz 5 V	VIPer01 Minimum ON time
100 (85 VAC)	5.0	0.83	1.67	
170V (120 VAC)	2.9	0.49	0.97	
325V (230 VAC)	1.5	0.26	0.50	0.35 μs
375V (265 VAC)	1.3	0.22	0.33	
622V (440 VAC)	0.8	0.13	0.26	

Lower frequency allows to handle the regulation even in the case of a very high ratio between input and output voltages

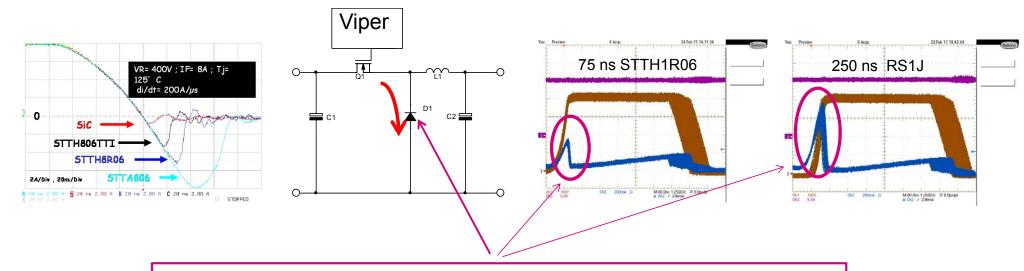


Minimum ON Time 31

- Duty cycle of Viper Buck converter is limited by minimum on time
 - Viper06 450 ns
 - Viper01 350 ns
- If the required ON time is shorter then minimum ON time, Buck still works, but there is small instability and the maximum deliverable output current is reduced.
- The 30kHz version is strictly recommended for 5V output

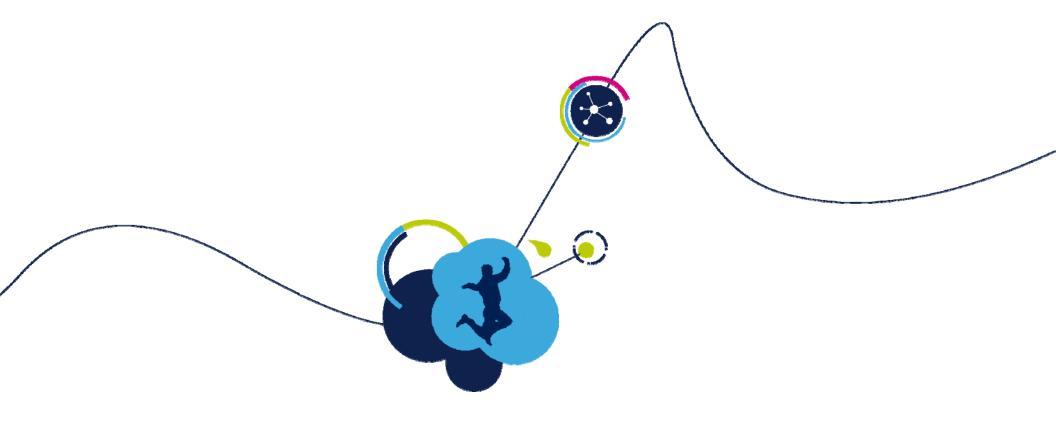


Diode Recovery Effect 32



Recovery effect causes short cross conduction ever turn ON. Effect is much critical in case CCM => **DCM** is recommended. The lost energy is higher at higher power operating frequency => The 30kHz version is recommended.





Layout and EMI Optimization



Layout Optimization 34

- Minimize interconnection lengths of following components:
 - Input filter caps, input-side transformer (or inductor), power MOSFET, sensing resistors and active-clamp or snubber circuits
 - Output-side transformer (or inductor), rectifier diodes and output filter caps
- Keep power and signal circuitries separated and careful of connection between the signal and power grounds
- Assure component isolation and spacing by safety standards
- Prioritize ground over all routes
- Compromise copper areas between Thermal and EMI
- Add sufficient VIAs for better thermal performance
- Keep the feedback path as far as possible from power components and noise traces
- External compensation components should be close to IC
- Copper traces for power should be thick and short and sharp angles should be avoided

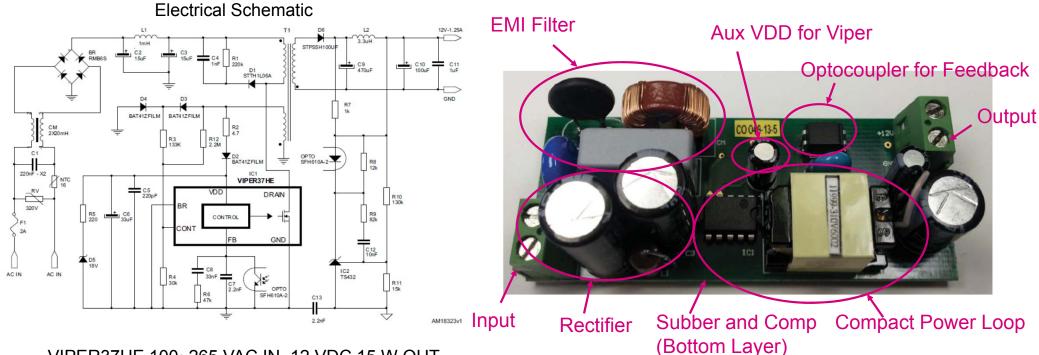


EMI Optimization 35

- EN 55022 is an European EMC standard applicable to information technology equipment with a rated supply voltage not exceeding 600 V
- Properly size EMI filter: differential mode filter for power < 5 W; X-, Y-caps, and common mode choke for power > 15 W
- Designers often use snubbers and soft switching techniques to minimize the EMI
- Shielded transformer has better EMI but also has larger leakage inductance
- Connect heatsinks to ground
- Focus on coupling paths from EMI sources to EMI sensitive components
- Strategic orientation and placement of components can reduce EMI generation significantly
- Eliminate environmental interference on EMI test
- Use an accurate EMI analyzer to carry quasi-peak, and average measurement to meet standards
- ST offers PWM operation with frequency jittering for low EMI



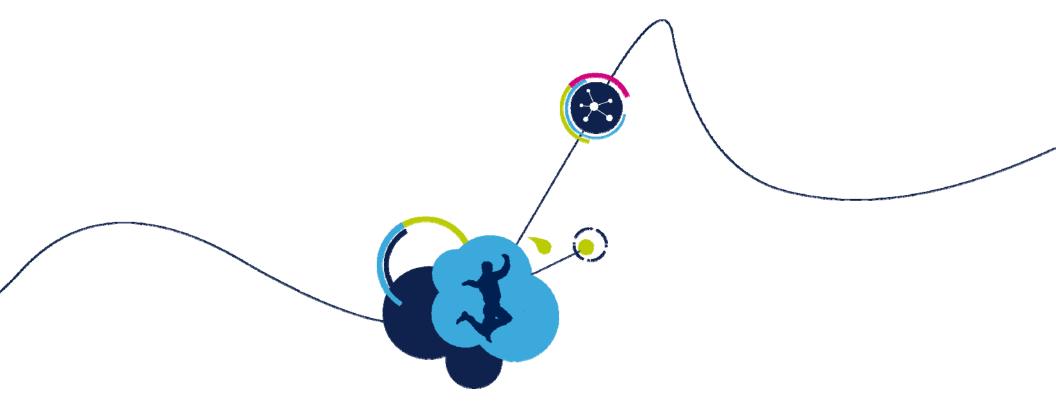
Design Example 36



VIPER37HE 100~265 VAC IN, 12 VDC 15 W OUT

Evaluation Board (30 x 72 mm) Max





eDesignSuite Examples



eDesignSuite eDs

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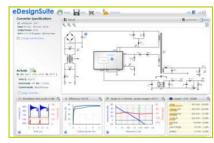
Open
eDesignSuite
off-line version
(ask to ST sales office)



Choose an application type and create your design



Insert your I/O specifications and select one of the proposed IC driver



The design is ready!

1

2

3

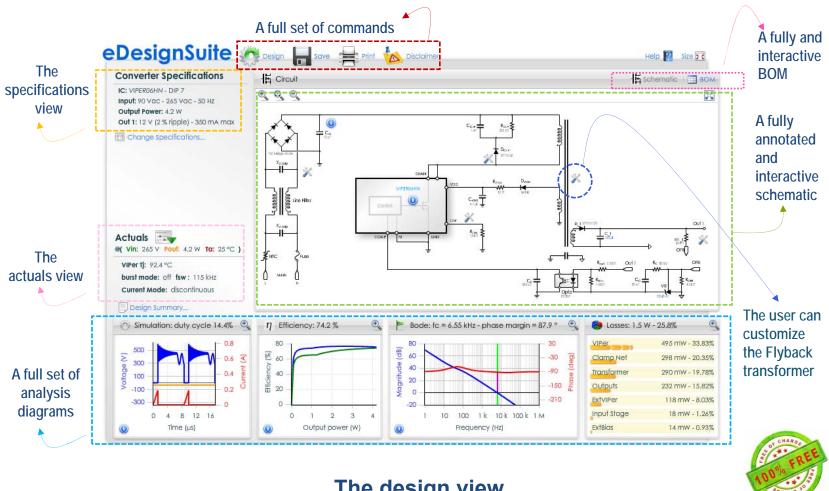
4



A complete design in a few steps

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The design view

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Thank you!

